



Product / Process Change Notice

No.: Z200-PCN-DM201701-02-A

Date: 01/24/2017

Change Title : W25Q80DL "D-Series" (90nm) to replace W25Q80BL "B-Series" (90nm) 8Mb 2.5V SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Assembly Packing Testing Others

Affected Product(s) :

W25Q80BLSNIG ,W25Q80BLSVIG ,W25Q80BLSSIG ,W25Q80BLZPIG ,W25Q80BLUXIG

Description of Change(s)

The W25Q80DL 8Mb 2.5V SpiFlash® Memories use Winbond's 90nm Flash technology. It is function-compatible W25Q80BL 90nm devices offering improved performance, features and availability.

Reason for Change(s) :

- a) Backward compatible with W25Q80BL
- b) Feature and function enhancement

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Concern (refer to Attachment I in details)

Reliability : No Change (refer to Attachment II in details)

Hazardous Substances: No Concern (refer to Attachment III in details)

Qualification Plan/ Results :

Based on Winbond W25Q80DL Serial Flash Reliability report, the new product meets our criteria and no quality concern. (refer to Attachment II in details)

Implementation Plan :

Please refer Attachment IV for more detail.

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: 04/25/2017

Originator: (QA)

Approval: (QA Dept. Manager)

Approval: (QRA Director)

Contact for Questions & Concerns

Name: Betty Huang TEL:886-3-5678168 (ext.86549) FAX:886-3-5796124
Address : # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan
E-mail: Hyhuang8@winbond.com



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

Dept. name: _____

Person in charge: _____



Winbond Electronics Corporation

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Product Obsolescence Notice

W25Q80DL SpiFlash Memories

Notification Date: January 23, 2017

Dear Valued Customer,

This letter is to notify you of Winbond's intention to terminate production of the W25Q80BL SpiFlash memory, and replace it with the W25Q80DL. Replacement part numbers are listed below:

Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm D-Series)
W25Q80BLSNIG	W25Q80DLSNIG
W25Q80BLSVIG	W25Q80DLSVIG
W25Q80BLSSIG	W25Q80DLSSIG
W25Q80BLZPIG	W25Q80DLZPIG
W25Q80BLUXIG	W25Q80DLUXIE

The W25Q80DL device features:

Features

- a) Backward compatible with W25Q80BL
- b) Feature and function enhancement

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q80BL	Jan./23/ 2017	Jul./25 2017	Jan./25/ 2018	W25Q80DL	Oct./2 2015	Jul./3 2015

Eddy Hung

Assistant Vice President of Flash Marketing